

SOLDER Paste RMA Series

SOLDER PASTE RMA Series is a solder paste which consists of RMA type flux satisfies QQ-S-571E and spherical solder powder with very little oxide. So flux residue after soldering becomes high reliable coating with excellent insulation resistance. And possible to use for 0.5 mm pitch such as QFP.

Advantage :

- It has an excellent permeability and most suitable for continuous printing.
- It can print very precisely on 0.5 mm pitch fine pattern to 0.8 mm pitch wide.
- Flux is high reliable so that solder balls are almost nothing and no need to wash.
- It has an excellent shelf life and can be kept at room temperature (below 20) .

Specifications :

Item	RMA-010		RMA-020		NRMA-010	NRMA-020
	T-312	T-322	T-312	T-322	T-432	
Alloy Compositions	N63/Pb37		Sn62/Ag2/Pb36		Sn63/Pb37	Sn62/Ag2/Pb36
Melting Point	183		179		183	179
Solder Power Mesh Size	38~63 μ m	38~45 μ m	38~63 μ m	38~45 μ m	20~38 μ m	
Flux Content	9wt %				8wt %	
Uses	For general electronic equipment		For prevention of silver dissolution		For N ₂ reflow	
	For general	For fine pattern	For general	For fine pattern	For fine pattern	

Features :

Item	RMA-A	Testing Method
Viscosity	2×10 ⁵ ~3×10 ⁵	PCU-2 25
Resistivity of water extract	15×10 ⁴ cm	QQ-S-571E
Chloride, Bromide	Passed	QQ-S-571E
Dryness	Passed	QQ-S-571E
Corrosion test on Copper Mirror	Passed	QQ-S-571E
Electric insulation resistance	1×10 ¹² or more	JIS Z 3197
Components mountability	24 hours	TAMURA Standard test method
Coefficient of spread	90 % or more	JIS Z 3197